

AD178A Datasheet

Zhuhai Jieli Technology Co.,LTD

Version: 1.0

Date: 2023.07.13

AD178A Features

CPU

- 32bit DSP
- Maximum speed 160MHz
- Interrupts with 8 priority level

Memory

- Optional built-in flash memory

Clocks

- On-chip 16 MHz clock
- On-chip 200KHz lower-temperature-drift clock

Audio APA

- Support for driving 4 or 8 ohm speaker
- Mono Class-D Speaker Amplifier
 - 0.42W/8 Ω @3.7V
 - 0.17W/8 Ω @2.4V
 - 0.62W/4 Ω @3.7V
 - 0.25W/4 Ω @2.4V

Peripherals

- Three multi-function 16-bit timers, support capture and PWM mode
- Two UART Controllers(UART0/1) supports DMA and Flow Control

- One IIC Master controller
- One SPI Master / Slaver controller with DMA
- 2-channel 10-bit general purpose ADC
- 4-channel Advance PWM controller
- 4 Individually programmable and multiplexed GPIO pins
- Digital peripheral crossbar
- Up to 4 external interrupt / wake-up source (low power available,can be multiplexed to any I/O)
- Watchdog

PMU

- Less than 2uA soft off current
- VBAT range : 2.0V to 5.5V
- IOVDD range : 2.0V to 3.4V

Packages

- SOP8

Temperature

- Operating temperature: -40°C to +85°C
- Storage temperature: -65°C to +150°C

Applications

- Sound Toy
- Audio player

1 Block Diagram

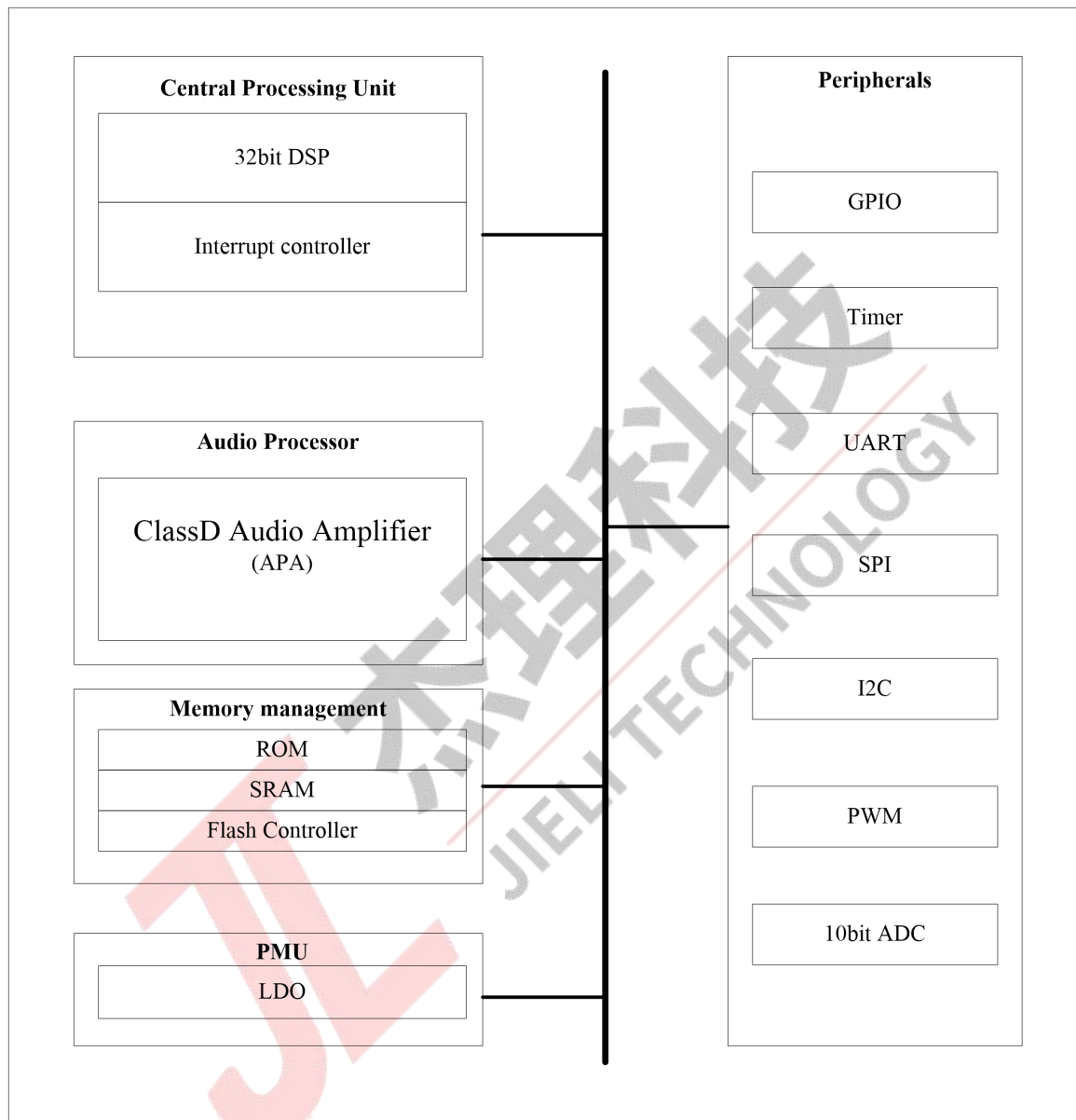


Figure 1-1 AD178A Block Diagram

2 Pin Definition

2.1 Pin Assignment

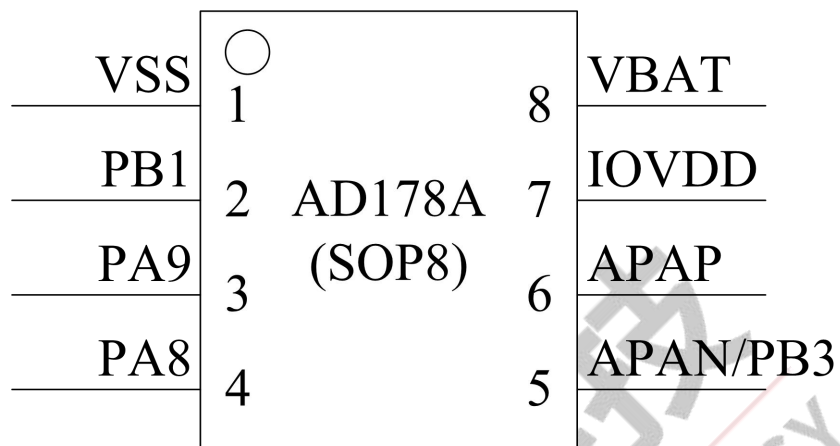


Figure 2-1 AD178A Package Diagram

2.2 Pin Description

Table 2-1 AD178A Pin Description

PIN NO.	Name	Type	Function	Other Function
1	VSS	G		System ground;
2	PB1	I/O	5V tolerant IO	Serial port code upgrade pin; APA_DOP;
3	PA9	I/O	GPIO (pull down)	ADC9:ADC Input Channel 9; Touch cap; CLK OUT2:Internal clock output2;
4	PA8	I/O	GPIO (pull down)	ADC8:ADC Input Channel 8; WKUP; CLK OUT1:Internal clock output1;
5	PB3	I/O	5V tolerant IO	
	APAN	O		Class-D APA Negative Output;
6	APAP	O		Class-D APA Positive Output;
7	IOVDD	PO	Power supply for GPIO	Built-in linear voltage regulator output;
8	VBAT	PI		Power supply input;

Pin Type	Description	Pin Type	Description
P	Power	I/O	Input or Output
PI	Power Input	I	Input
PO	Power Output	O	Output
AO	Analog Output	G	Ground

3 Electrical Characteristics

3.1 Absolute Maximum Ratings

Table 3-1

Symbol	Parameter	Min	Max	Unit
T _{opt}	Operating temperature	-40	+85	°C
T _{stg}	Storage temperature	-65	+150	°C
V _{BAT}	Supply Voltage	-0.3	6	V
V _{IOVDD}	Voltage applied at IOVDD	-0.3	3.6	V
V _{GPIO}	Voltage applied to GPIO	-0.3	IOVDD+0.3	V
V _{HVIO}	Voltage applied to High Voltage Resistant IO	-0.3	+5.5	V

Note : The chip can be damaged by any stress in excess of the absolute maximum ratings listed below

3.2 PMU Characteristics

Table 3-2

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V _{BAT}	Voltage Input	2.0	3.7	5.5	V	—
IOVDD	Voltage output	2.0	3.0	3.4	V	V _{BAT} = 4.2V, 10mA loading
	Loading current	—	—	100	mA	IOVDD=3.3V@V _{BAT} ≥ 3.6V
V _{LVD}	Voltage input	1.8	2.5	2.5	V	Low-Voltage Detection of IOVDD

3.3 IO Input/Output Electrical Logical Characteristics

Table 3-3

GPIO input characteristics						
Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V _{IL}	Low-Level Input Voltage	-0.3	—	0.3* IOVDD	V	IOVDD = 3.0V
V _{IH}	High-Level Input Voltage	0.7* IOVDD	—	IOVDD+0.3	V	IOVDD = 3.0V
High Voltage Resistant IO input characteristics						
Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V _{IL}	Low-Level Input Voltage	-0.3	—	0.3* IOVDD	V	IOVDD = 3.0V
V _{IH}	High-Level Input Voltage	0.7* IOVDD	—	+5V	V	IOVDD = 3.0V
Resistant IO output characteristics						
Symbol	Parameter	GPIO		Typ	Unit	Test Conditions
V _{OL}	0.1*IOVDD Drive current	PA8,PA9		HD=1 : -7 HD=2 : -22 HD=3 : -27	mA	IOVDD = 3.0V
		PB1,PB3		-7		
	0.1*HPVDD Drive current APA IO total current limit of 200mA	APAN APAP		-200		V _{BAT} =3.7V

V _{OH}	0.9*IOVDD Drive current	PA8,PA9	HD=1 : 7 HD=2 : 24 HD=3 : 56	mA	IOVDD = 3.0V
		PB1,PB3	7		
	0.9*HPVDD Drive current APA IO total current limit of 200mA	APAN APAP	200		VBAT=3.7V

3.4 Internal Resistor Characteristics

Table 3-4

Port	Internal Pull-Up Resistor	Internal Pull-Down Resistor	Comment
PA8,PA9,PB1,PB3	10K	200K	1. PA8~PA9 default pull down 2. Internal pull-up/pull-down resistance accuracy ±20%

3.5 Audio APA Characteristics

Table 3-5

Parameter	MODE	Min	Typ	Max	Unit	Test Conditions	
Frequency Response		20	—	20K	Hz	R _L =10K, VBAT=3.7V	
Output Swing	Diff (N to P)	—	1.57	—	Vrms	R _L =4Ω	f=1kHz/0dB VBAT=3.7V
		—	1.83	—	Vrms	R _L =8Ω	
		—	2.22	—	Vrms	R _L =10K	
	Single-ended	—	1.11	—	Vrms	R _L =10K	
	Diff (N to P)	—	0.99	—	Vrms	R _L =4Ω	f=1kHz/0dB VBAT=2.4V
		—	1.17	—	Vrms	R _L =8Ω	
		—	1.44	—	Vrms	R _L =10K	
	Single-ended	—	0.72	—	Vrms	R _L =10K	
Output power	Diff (N to P)	—	0.62	—	W	R _L =4Ω	f=1kHz/0dB
		—	0.42	—	W	R _L =8Ω	VBAT=3.7V
		—	0.25	—	W	R _L =4Ω	f=1kHz/0dB
		—	0.17	—	W	R _L =8Ω	VBAT=2.4V
THD+N	Diff (N to P)	—	-31	—	dB	R _L =4Ω	f=1kHz/0dB A-Weighted VBAT=3.7V
		—	-35	—	dB	R _L =8Ω	
		—	-75	—	dB	R _L =10K	
	Single-ended	—	-70	—	dB	R _L =10K	
	Diff (N to P)	—	-31	—	dB	R _L =4Ω	f=1kHz/0dB A-Weighted VBAT=2.4V
		—	-36	—	dB	R _L =8Ω	
		—	-73	—	dB	R _L =10K	
	Single-ended	—	-70	—	dB	R _L =10K	
S/N	Diff (N to P)	—	97	—	dB	R _L =4Ω	f=1kHz/0dB A-Weighted VBAT=3.7V
		—	97	—	dB	R _L =8Ω	
		—	95	—	dB	R _L =10K	
	Single-ended	—	75	—	dB	R _L =10K	

S/N	Diff (N to P)	—	94	—	dB	$R_L=4\Omega$	f=1kHz/0dB A-Weighted VBAT=2.4V
		—	94	—	dB	$R_L=8\Omega$	
		—	88	—	dB	$R_L=10K$	
	Single-ended	—	72	—	dB	$R_L=10K$	
Dynamic Range	Diff (N to P)	—	88	—	dB	$R_L=4\Omega$	f=1kHz/-60dB A-Weighted VBAT=3.7V
		—	88	—	dB	$R_L=8\Omega$	
		—	86	—	dB	$R_L=10K$	
	Single-ended	—	75	—	dB	$R_L=10K$	
	Diff (N to P)	—	87	—	dB	$R_L=4\Omega$	f=1kHz/-60dB A-Weighted VBAT=2.4V
		—	87	—	dB	$R_L=8\Omega$	
		—	85	—	dB	$R_L=10K$	
	Single-ended	—	74	—	dB	$R_L=10K$	

4 Package Information

4.1 SOP8

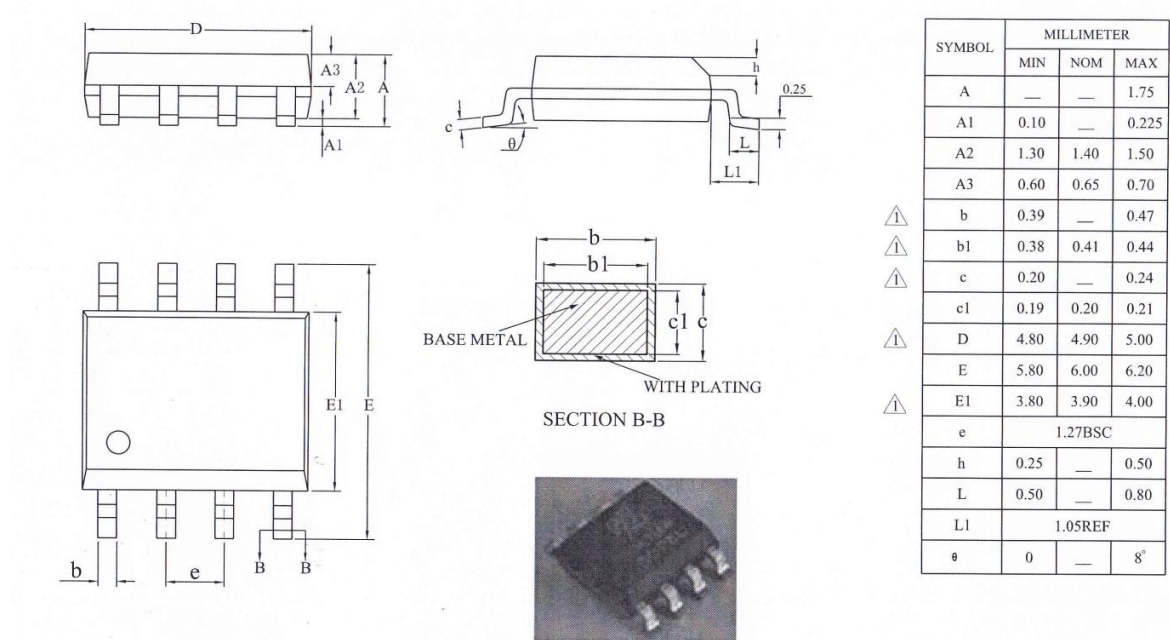
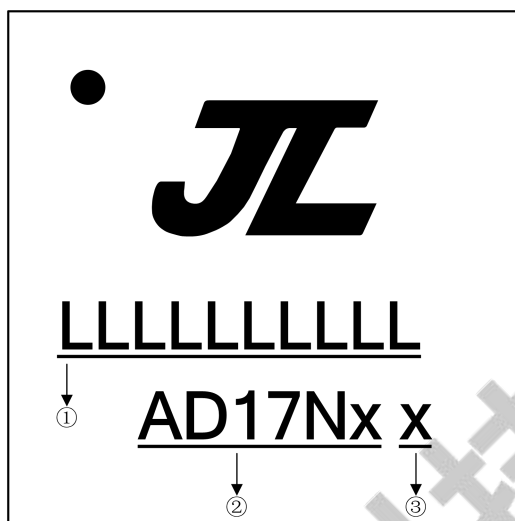


Figure 4-1 AD178A Package

5 IC Marking Information



① LLLLLLLLLL : Production Batch

② AD17Nx : Chip Model

③ Built-in flash size

0: No Flash Memory

2: 2Mbit Flash

4: 4Mbit Flash

8: 8Mbit Flash

6: 16Mbit Flash

3: 32Mbit Flash

6 Solder-Reflow Condition

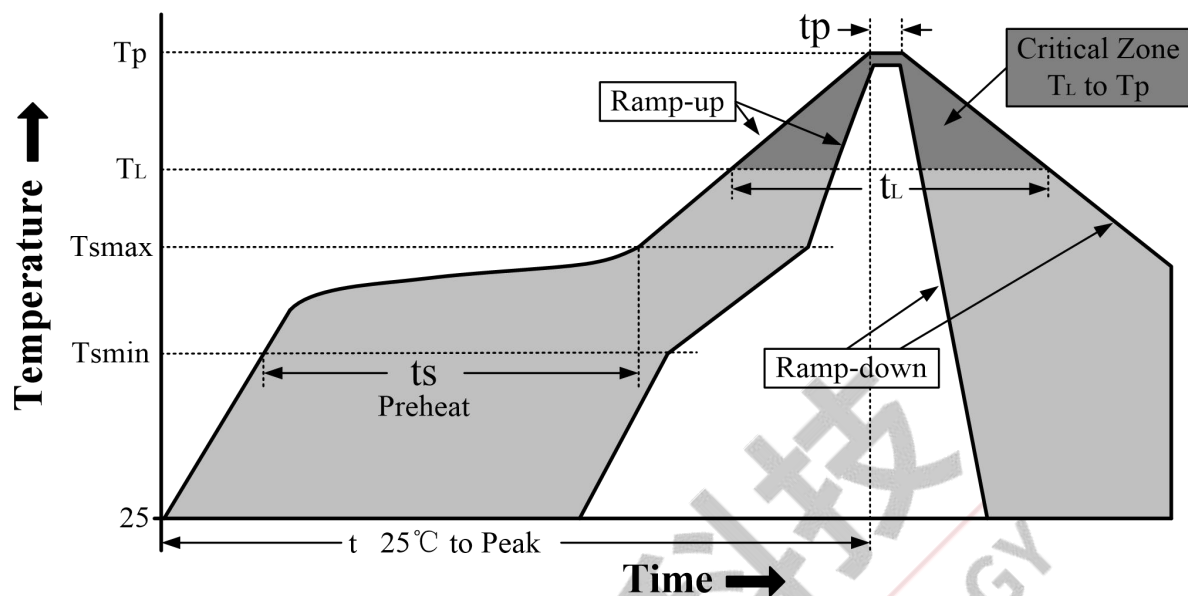


Figure 6-1 Classification Reflow Profile

Classification Profiles

Table 6-1

Profile Feature		Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat/ Soak	Temperature Min (T_{smin})	100 °C	150 °C
	Temperature Max (T_{smax})	150 °C	200 °C
	Time (t_s) from (T_{smin} to T_{smax})	60-120 seconds	60-180 seconds
Average ramp-up rate (T_{smax} to T_p)		3 °C/second max	3 °C/second max
Liquidous temperature (T_L)		183 °C	217 °C
Time (t_L) maintained above T_L		60-150 seconds	60-150 seconds
Peak package body temperature (T_p)		See Table 6-2.	See Table 6-3.
Time within 5°C of actual Peak Temperature (t_p)		10-30 seconds	20-40 seconds
Ramp-down rate (T_p to T_L)		6 °C/second max.	6 °C/second max.
Time 25 °C to peak temperature		6 minutes max.	8 minutes max.

Note 1: All temperatures refer to topside of the package, measured on the package body surface.

Note 2: Time within 5°C of actual peak temperature (t_p) specified for the reflow profiles is a “supplier” minimum and “user” maximum.

SnPb - Classification Temperature

Table 6-2

Package Thickness	Volume mm ³ < 350	Volume mm ³ ≥ 350
<2.5 mm	240 +0/-5 °C	225 +0/-5 °C
≥ 2.5 mm	225 +0/-5 °C	225 +0/-5 °C

Pb-free - Classification Temperature **Table 6-3**

Package Thickness	Volume mm ³ < 350	Volume mm ³ 350 - 2000	Volume mm ³ > 2000
< 1.6mm	260 °C	260 °C	260 °C
1.6 mm - 2.5mm	260 °C	250 °C	245 °C
> 2.5mm	250 °C	245 °C	245 °C

7 Revision History

Date	Revision	Description
2023.07.13	V1.0	Initial Release.

